

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Cancelled)
2. (Cancelled)
3. (Currently Amended) An apparatus comprising:  
an integrated circuit package;  
an integrated circuit die coupled to the integrated circuit package; and  
a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed;  
a thermally-conductive material disposed in the well and in contact with the stiffener portion and the integrated circuit die; and  
a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material, the thermally conductive material disposed between the integrated circuit die and the heat sink.
4. (original) An apparatus according to Claim 3, further comprising:  
underfill material disposed between the integrated circuit die and the integrated circuit package.
5. (Cancelled)

6. (Cancelled)

7. (Withdrawn) A method comprising:

placing a plurality of integrated circuit die on respective ones of a plurality of mounting locations of an integrated circuit package substrate; and

placing a stiffener strip on the integrated circuit package substrate,

wherein the plurality of integrated circuit die and the plurality of mounting locations are disposed in respective ones of a plurality of openings defined by the stiffener strip.

8. (Withdrawn) A method according to Claim 7, further comprising:

soldering the plurality of integrated circuit die to the respective mounting locations.

9. (Withdrawn) A method according to Claim 8, further comprising:

dispensing underfill material on the integrated package substrate adjacent to one or more of the mounting locations.

10. (Withdrawn) A method according to Claim 7, further comprising:

singulating one of the plurality of integrated circuit die and a respective mounting location of the integrated package substrate.

11. (Currently Amended) A system comprising:

a microprocessor comprising:

an integrated circuit package;

an integrated circuit die coupled to the integrated circuit package; and

a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed;

a thermally-conductive material disposed in the well and in contact with the stiffener portion and the integrated circuit die;

a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material, the thermally conductive material disposed between the integrated circuit die and the heat sink; and

a double data rate memory electrically coupled to the microprocessor.

12. (Cancelled)

13. (Cancelled)

14. (original) A system according to Claim 11, further comprising:  
a motherboard electrically coupled to the microprocessor and to the memory.